

IEEE 2024 OA 投稿優惠詳解與操作流程

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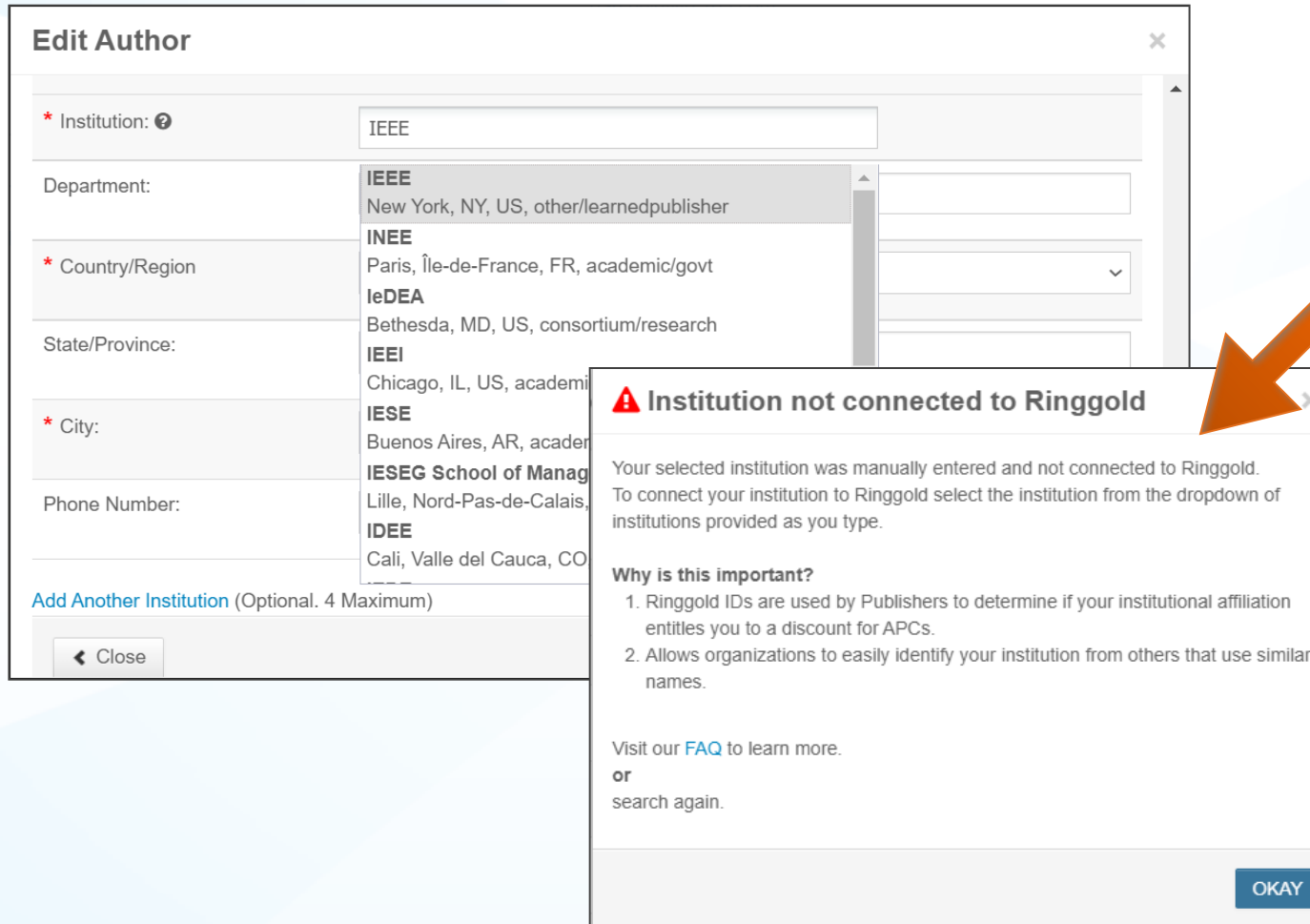
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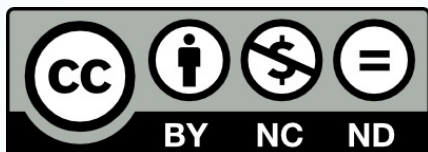
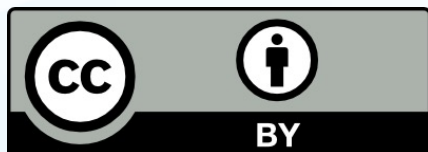
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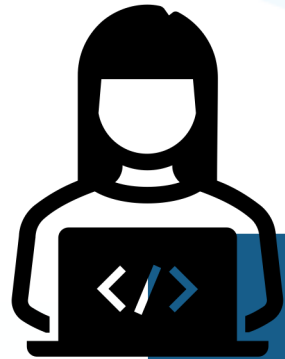
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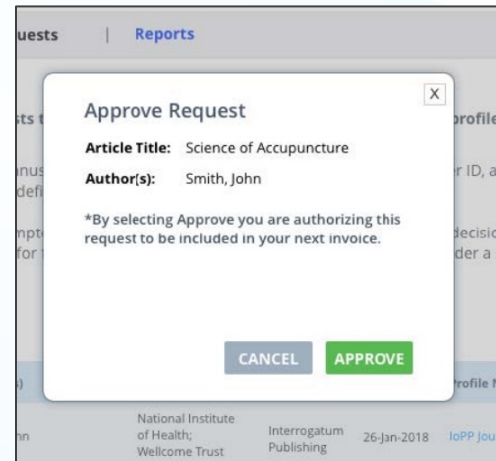
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